

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S3	3534	257/758.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 01:22
S6	2841	257/758.ccls. and @ad<"20030225"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/12/12 01:24
S7	2325	257/758.ccls. and @ad<"20030225"	USPAT; EPO; JPO	OR	ON	2005/12/12 01:24
S11	1036	(257/758 or 257/759).ccls. and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 01:26
S8	1834	257/758.ccls. and @ad<"20030225"	USPAT	OR	ON	2005/12/12 01:59
S12	1145	257/758.ccls. and @ad<"20030225" not S11	USPAT	OR	ON	2005/12/12 02:00
S10	1007	257/758.ccls. and @ad<"20030225"	US-PGPUB; EPO; JPO	OR	ON	2005/12/12 02:20
S13	756	257/758.ccls. and @ad<"20030225" not S11	US-PGPUB; EPO; JPO	OR	ON	2005/12/12 02:20
S4	2841	257/758.ccls. and @ad<"20030225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 02:27
S5	940	257/758.ccls. and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 02:27
S14	1960	257/773.ccls. and @ad<"20030225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 02:27

S15	606	257/773.ccls. and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 02:27
S16	505	257/773.ccls. and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5) not S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 02:30
S17	41203	semiconductor and (ILD or interlayer or MLM or multilayer\$4 or metallization or interconnect or multilevel) and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5) not S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 02:31
S18	572	semiconductor and (ILD or interlayer or MLM or multilayer\$4 or metallization or interconnect or multilevel) and @ad<"20030225" and ((pillar or post or dummy) with (stress\$4 or reinforc\$5))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 02:31
S19	1103	semiconductor and (ILD or interlayer or MLM or multilayer\$4 or metallization or interconnect or multilevel) and @ad<"20030225" and ((pillar or post or dummy) same (stress\$4 or reinforc\$5))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 02:31
S20	1053	semiconductor and (ILD or interlayer or MLM or multilayer\$4 or metallization or interconnect or multilevel) and @ad<"20030225" and ((pillar or post or dummy) not S5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 02:33